

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 12 of the application and as previously amended as follows:

ABSTRACT OF THE DISCLOSURE

A method of forming a semiconductor package is provided. The method includes forming a leadframe wherein the conductors or leads of the leadframe extend from a first end to a second end such that a portion of each lead exhibits a generally arcuate shape. The first end may be coupled with a printed circuit board and the second end may be coupled with a semiconductor die. The generally-arcuately shaped-arcuately shaped portion of the leads may include a portion which exhibits a constant radius. The generally-arcuately shaped-arcuately shaped portion may also be formed from a plurality of conductor segments including, for example, at least one generally-arcuately shaped-arcuately shaped segment. The semiconductor die and at least a portion of the leads may be encapsulated with an insulating material.